



## P-Channel Enhancement Mode MOSFET

### ➤ Features

VDS	VGS	RDSON Typ.	ID
-20V	±12V	14mR@-4V5	-10A
		20mR@-2V5	

### ➤ Description

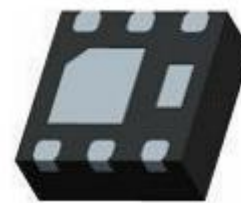
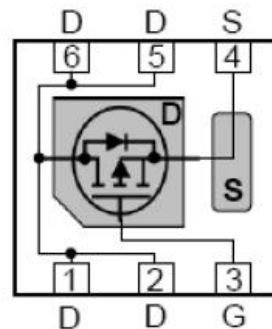
This device is produced with high cell density DMOS trench technology, which is especially used to minimize on-state resistance. This device particularly suits low voltage applications such as portable equipment, power management and other battery powered circuits.

### ➤ Applications

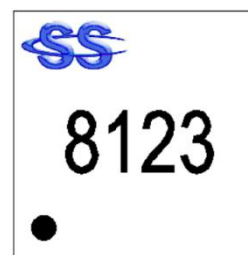
- Load Switch
- Portable Devices
- DCDC conversion
- Charging
- Driver for Relay

### ➤ Pin configuration

Top view



Bottom View



Marking

### ➤ Ordering Information

Device	Package	Shipping
SSC8123GN2	DFN2x2	3000/Reel



➤ **Absolute Maximum Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	-20	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 12$	V
$I_D$	Continuous Drain Current <sup>a</sup>	-10	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	-40	A
$P_D$	Power Dissipation <sup>c</sup>	2.7	W
$T_J$	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	45	$^{\circ}\text{C}/\text{W}$

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design.
- Repetitive rating, pulse width limited by junction temperature  $T_{J(MAX)}=150^{\circ}\text{C}$ .
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using steady state junction-to-ambient thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

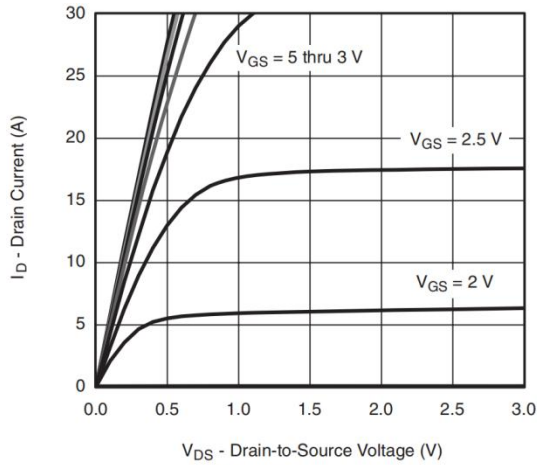


➤ **Electronics Characteristics**( $T_A=25^{\circ}\text{C}$  unless otherwise noted)

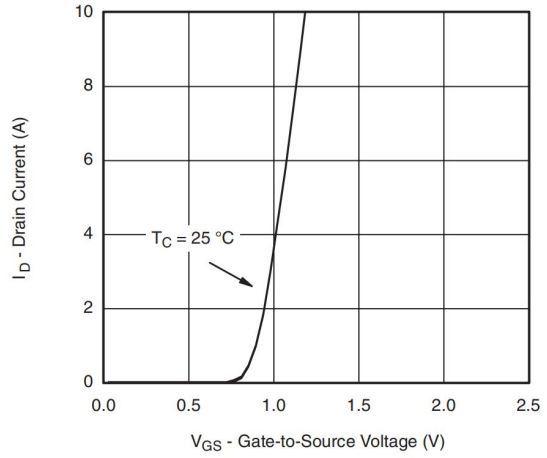
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-0.7	-1	V
$R_{DS(on)}$	Drain-Source On-Resistance	$V_{GS}=-4.5V, I_D=-4.5A$		14	20	mR
		$V_{GS}=-2.5V, I_D=-2.5A$		20	29	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=-16V, V_{GS}=0V$			-1	$\mu A$
$I_{GSS}$	Gate-Source leak current	$V_{GS}=\pm 12V, V_{DS}=0V$			$\pm 100$	nA
$G_{FS}$	Transconductance	$V_{DS}=-5V, I_D=-10A$		20		S
$V_{SD}$	Forward Voltage	$V_{GS}=0V, I_S=-2.2A$		-0.8	-1.3	V
$R_g$	Gate resistance	$V_{DS}=0V, f=1MHz$		2.7		R
$C_{iss}$	Input Capacitance	$V_{DS}=-10V, V_{GS}=0V, f=1MHz$		1520		pF
$C_{oss}$	Output Capacitance			182		
$C_{rss}$	Reverse Capacitance			158		
$T_{D(ON)}$	Turn-on delay time	$V_{GS}=-4.5V,$ $V_{DS}=-10V, R_L=1R$ $R_G=3R$		12		ns
$T_r$	Rise time			22		
$T_{D(OFF)}$	Turn-off delay time			45		
$T_f$	Fall time			23		
$Q_g$	Total Gate charge	$V_{GS}=-4.5V, V_{DS}=-10V$ $I_D=-10A$		16		nC
$Q_{gs}$	Gate Source charge			3		
$Q_{gd}$	Gate Drain charge			4		
$t_{rr}$	Reverse Recovery Time	$I_F=-10A, dI/dt=100A/\mu s$		15		ns
$Q_{rr}$	Reverse Recovery Charge	$I_F=-10A, dI/dt=100A/\mu s$		6		nC



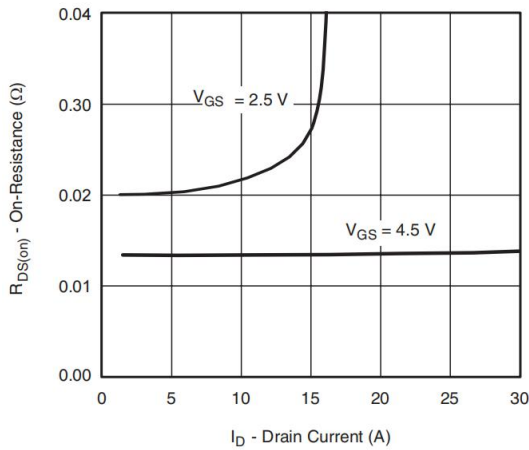
➤ **Typical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise noted)



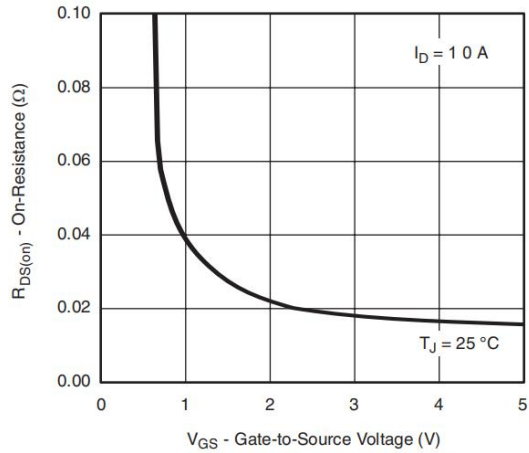
**Output Characteristics**



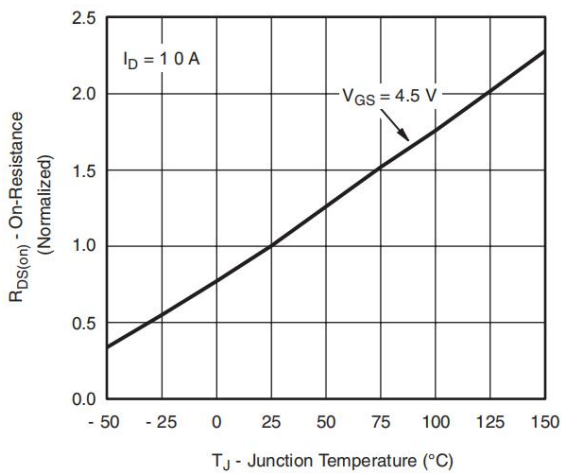
**Transfer Characteristics**



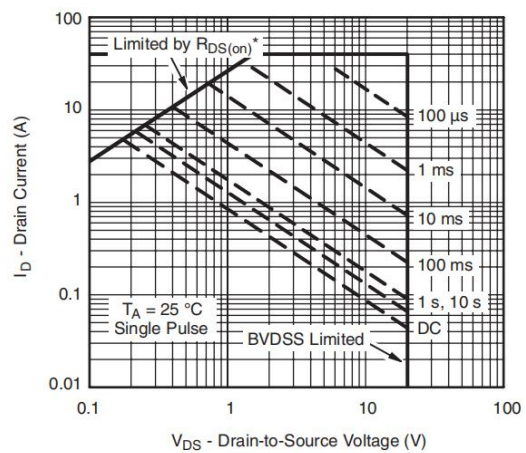
**On-Resistance vs. Drain Current**



**On-Resistance vs. Gate-to-Source Voltage**



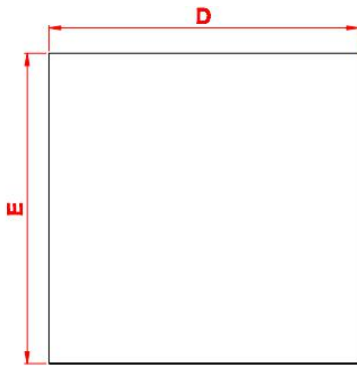
**On-Resistance vs. Junction Temperature**



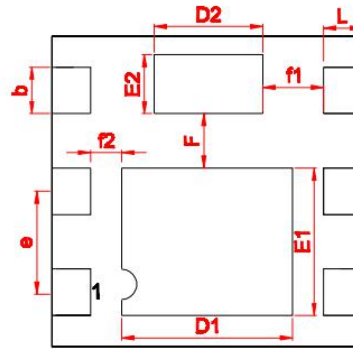
**Safe Operating Area, Junction-to-Ambient**



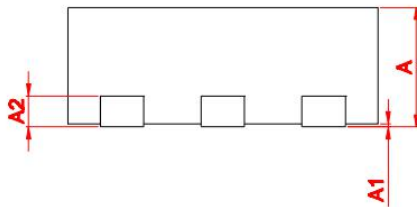
➤ Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.700	0.750	0.800
* A1	0.000	0.020	0.050
* b	0.250	0.300	0.350
* A2	0.190	0.210	0.230
* D	1.900	2.000	2.100
* E	1.900	2.000	2.100
* E1	0.900	0.950	1.000
* E2	0.330	0.380	0.430
* D1	1.100	1.150	1.200
* D2	0.650	0.700	0.750
* e	0.600	0.650	0.700
* L	0.225	0.250	0.275
* F	0.300	0.350	0.400
* f1	0.350	0.400	0.450
* f2	0.180	0.200	0.220



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